

ABSTRACT OF THE DISCLOSURE

ELECTRONIC COMPONENT, METHOD FOR PRODUCING ELECTRONIC COMPONENT, AND APPARATUS FOR PRODUCING ELECTRONIC COMPONENT

The present invention is intended to produce an electronic component that favorably shields an electromagnetic wave and has favorable heat radiation with high productivity.

A packaging substrate 22 equipped with plural electronic devices 3 on its principal surface 23 is disposed on an upper die 14, and a conductor-formed plate-like member 24 on which a projected conductive member 21 is formed is disposed on the inner bottom surface of a cavity 16 of a lower die 15. The upper part of the conductive member 21 is caused to be exposed from a liquid resin 20 filled in the cavity 16. The conductive member 21 is caused to be bent and brought into contact with a ground wiring pattern 9 by clamping the upper die 14 and the lower die 15; a metal thin wire 11, the electronic devices 3, the principal surface 23 of the packaging substrate 22, and the like are immersed in the liquid resin 20; an encapsulation resin 4 is formed by curing the liquid resin 20 to complete an encapsulated substrate 26. The encapsulated substrate 26 is divided into individual pieces to produce electronic components. The conductive member 21 and the ground wiring pattern 9 are electrically connected securely in the state where the conductive member 21 is pressed toward the ground wiring pattern 9 by the compressive stress at the time of curing the liquid resin 20.

Fig. 4